

High-performance Liquid Cooling Heat Sink

Thermal Management Solution

Our high-performance liquid cooling heat sink with connectors is suitable for heat dissipation of high-power components with tight packaging constraints. With low thermal resistance, our robust and cost-effective solution is customizable to your end application needs.

Low Thermal Resistance

$<0.035^{\circ}\text{C/W}$ at 1 LPM
with PG25 coolant while
pressure drop is <0.05 BAR

Material Combination Available

Such as aluminum
and copper

Customized Connectors

Customized based on
end applications

High-strength Thermoplastic Encapsulation

Liquid flow is sealed by
glass-fiber reinforced
thermoplastic material where
absolute pressure of 5 BAR is
reached without any leakage
and rupture

Increased Surface-area-to-volume Ratio



Staggered Copper Pin Fins
(0.8 mm thick, 2 mm pitch)

Applications

- Battery Cooling Plate
- Power Inverter
- CPU Cooler
- Avionics

Industries



e-Mobility &
Automotive



Information &
Communications
Technology



Aerospace